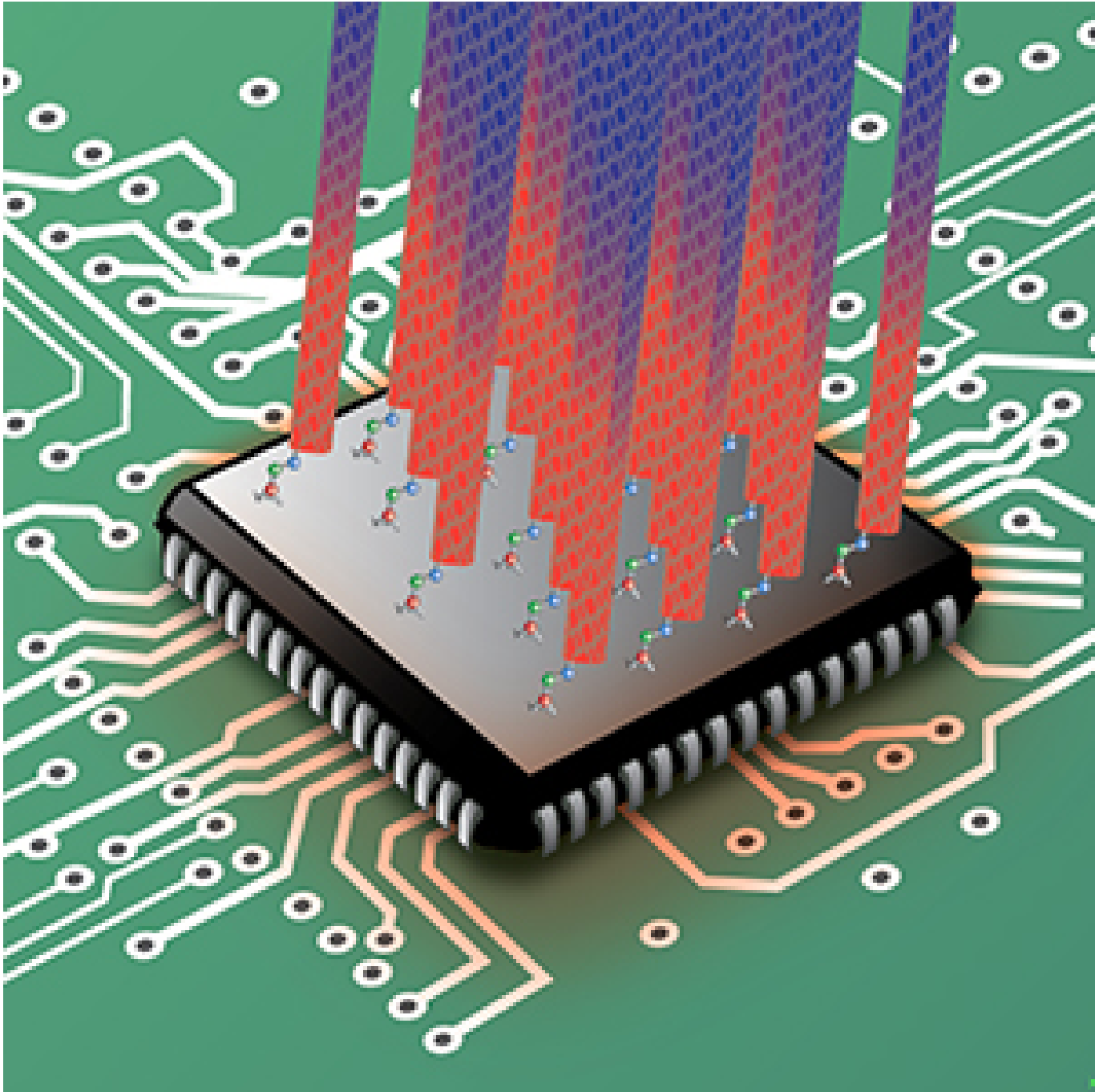


Photos of the Day: Cooling Microprocessors

Lynn Yarris, Lawrence Berkeley National Laboratory

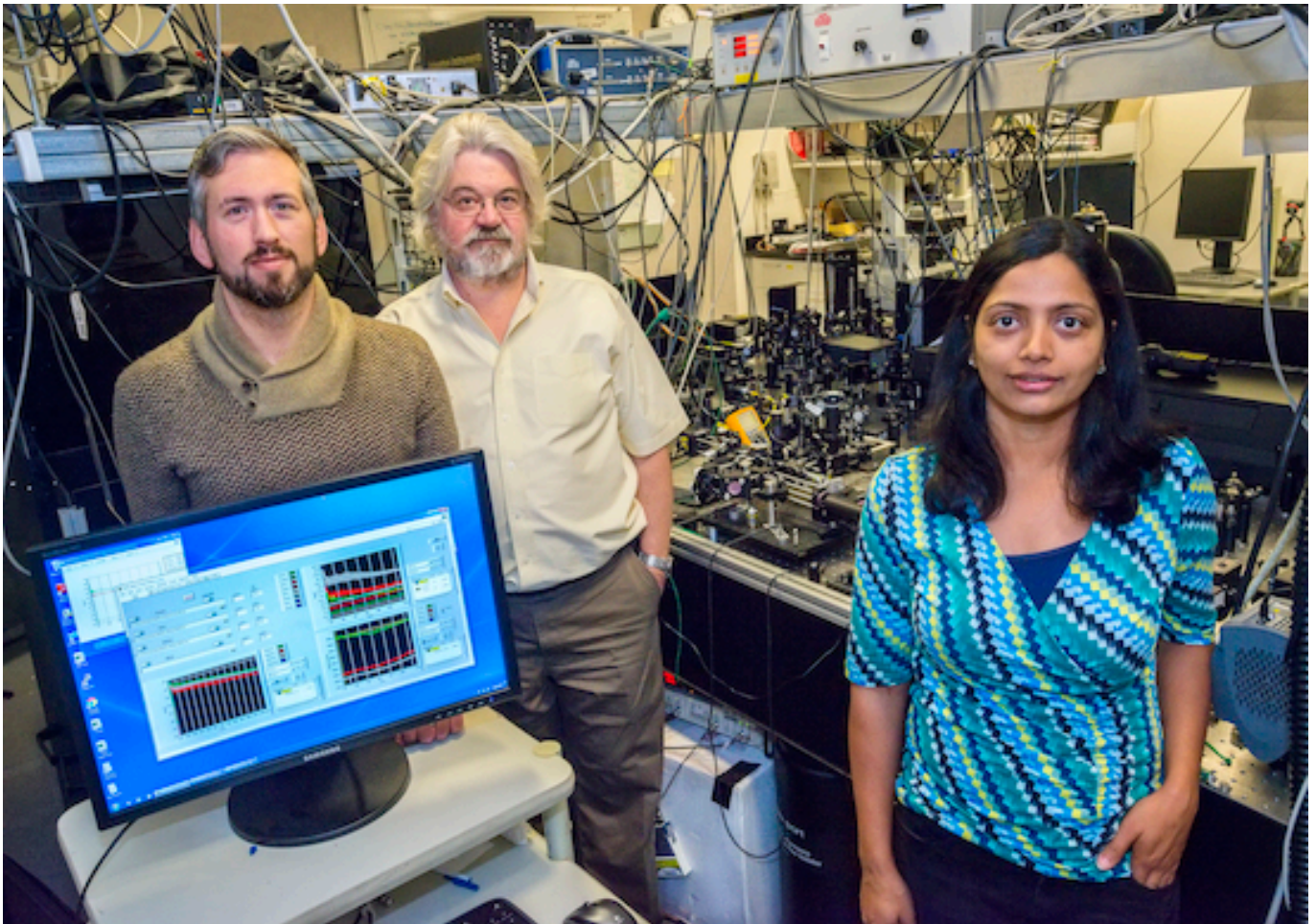


Cooling microprocessor chips through the combination of carbon nanotubes and organic molecules as bonding agents is a promising technique for maintaining the performance levels of densely packed, high-speed transistors in the future.

Read: [Cooling Microprocessors with Carbon Nanotubes](#) [1]

Photos of the Day: Cooling Microprocessors

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From left, Brett Helms, Frank Ogletree and Sumanjeet Kaur at the Molecular Foundry used organic molecules to form strong covalent bonds between carbon nanotubes and metal surfaces, improving by six-fold the flow of heat from the metal to the carbon nanotubes. (Photo by Roy Kaltschmidt)

For more information visit <http://www.lbl.gov> [2].

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[1] <http://www.wirelessdesignmag.com/news/2014/01/cooling-microprocessors-carbon-nanotubes>

[2] <http://www.lbl.gov/>